## King's College London

## University of London

This paper is part of an examination of the College counting towards the award of a degree. Examinations are governed by the College Regulations under the authority of the Academic Board.

M.Sci. EXAMINATION

CP/4474 Physics at the Nanoscale

Summer 2005

Time allowed: THREE Hours

Candidates must answer THREE questions. No credit will be given for answering further questions.

The approximate mark for each part of a question is indicated in square brackets.

You must not use your own calculator for this paper. Where necessary, a College calculator will have been supplied.

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## **Physical Constants**

Permittivity of free space	$\epsilon_0 =$	$8.854 \times 10^{-12}$	$\mathrm{F}\mathrm{m}^{-1}$
Permeability of free space	$\mu_0 =$	$4\pi \times 10^{-7}$	$\mathrm{H}\mathrm{m}^{-1}$
Speed of light in free space	c =	$2.998\times10^{8}$	${ m ms^{-1}}$
Gravitational constant	G =	$6.673 \times 10^{-11}$	$N\mathrm{m}^2\mathrm{kg}^{-2}$
Elementary charge	e =	$1.602 \times 10^{-19}$	$\mathbf{C}$
Electron rest mass	$m_{\rm e} =$	$9.109 \times 10^{-31}$	kg
Unified atomic mass unit	$m_{\rm u} =$	$1.661\times10^{-27}$	kg
Proton rest mass	$m_{\rm p} =$	$1.673 \times 10^{-27}$	kg
Neutron rest mass	$m_{\rm n} =$	$1.675 \times 10^{-27}$	kg
Planck constant	h =	$6.626 \times 10^{-34}$	$\mathrm{J}\mathrm{s}$
Boltzmann constant	$k_{\mathrm{B}}=$	$1.381\times10^{-23}$	$ m JK^{-1}$
Stefan-Boltzmann constant	$\sigma =$	$5.670\times10^{-8}$	${ m W}{ m m}^{-2}{ m K}^{-4}$
Gas constant	R =	8.314	$\mathrm{J}\mathrm{mol}^{-1}\mathrm{K}^{-1}$
Avogadro constant	$N_{ m A} =$	$6.022\times10^{23}$	$\mathrm{mol}^{-1}$
Molar volume of ideal gas at STP	=	$2.241\times10^{-2}$	$\mathrm{m}^3$
One standard atmosphere	$P_0 =$	$1.013\times10^{5}$	$ m Nm^{-2}$
Bohr magneton	$\mu_B =$	$9.274 \times 10^{-24}$	$ m J~T^{-1}$

GaAs has a direct energy gap of 1.43 eV, a relative permittivity of  $\epsilon = 10.9$ , and a lattice constant of 0.565 nm. Its electron, heavy hole and light hole effective masses are 0.072, 0.6 and 0.15 times the free electron mass  $m_0$ .

## **Answer THREE questions**

1)

a) A thin *strained* layer of one semiconductor is grown inside a second semiconductor of larger energy gap and smaller lattice spacing. Describe, and explain qualitatively, the effect of the strain on the energy gap of the thin layer.

[3 marks]

b) Explain why there is a practical limit to the thickness of a strained layer of semiconductor.

[3 marks]

c) A quantum well of GaAs is sandwiched between thick layers of an AlGaAs alloy which is *lattice-matched* to the GaAs. Electrons and holes are assumed to have free-particle behaviour for motion in the x, y plane of the layer, and wavefunctions of the form  $\sin(\pi z n/a)$  where n is an integer. Show that light travelling in the direction perpendicular to the plane of the layer can only be absorbed in the layer by creating electrons and holes with the same values of n.

[6 marks]

Data for GaAs are given at the head of the paper.

d) Assuming that a particle of mass m in an infinitely deep potential well of width a has energy levels

$$E = \frac{h^2}{8ma^2}n^2, \quad n = 1, 2...,$$

estimate, giving your answer in eV, the lowest photon energy  $(h\nu)$  of the light that can be absorbed in a GaAs layer of thickness 5 nm.

[3 marks]

e) What is the rate of change of the photon energy  $h\nu$  with the thickness a of the layer? A layer is grown on a < 001 > crystallographic surface of the substrate. Its thickness in places is 5 nm, but in other places it is greater by an amount equal to the smallest separation of two Ga atoms in the < 001 > direction. What is the fractional variation in  $h\nu$  across the plane?

[3 marks]

2)

a) A lattice-matched quantum layer of  $Ga_xIn_{1-x}Sb$  is buried inside AlSb. The AlSb is doped so that the layer is n-type. A magnetic field is applied in the z direction, defined as being perpendicular to the plane of the layer. The separation of the Landau levels (from a spin-up state to a spin-up state) is 40.6 meV at a field of 21 T. Calculate the value of the effective mass of the electrons at that field.

[5 marks]

b) Show that, per unit area of the layer, there are  $g(E) dE = m^*/(\pi \hbar^2) dE$  electron states in the energy range E to E + dE, where  $m^*$  is the effective mass of the electrons. If the layer contains  $n_A = 5 \times 10^{10}$  cm<sup>-2</sup> electrons, calculate the magnetic field  $B_1$  at which the lowest pair of Landau levels (i.e. with spin up and spin down) is filled.

[5 marks]

c) With the magnetic field on the z axis, an electrical current flows through the layer in the x direction and a Hall voltage is generated along the y axis. The transverse resistance of the layer is defined as  $\rho_T = E_y/J_x$  where  $E_y$  is the electric field created by the Hall effect and  $J_x$  is the current flowing divided by the width of the layer in the y direction. Show that at the field  $B_1$ ,  $\rho_T$  does not depend on the doping level  $n_A$ , on the effective mass  $m^*$  or on the dimensions of the layer. Calculate the value of  $\rho_T$  for the quantum layer at the field  $B_1$ . What is the practical value of this result?

[10 marks]

3)

a) Show that in a quantum wire there are g(E) dE electron states per unit length bewteen energies E and E + dE where

$$g(E) = \frac{1}{h} \sqrt{\frac{2m^*}{E}},$$

where  $m^*$  is the effective mass of the electrons.

[4 marks]

b) Defining the group velocity as  $v_g = d\omega/dk$ , show that the product of the  $v_g$  and g(E) is independent of the energy of the electrons and the properties of the quantum wire.

[4 marks]

c) Justify, qualitatively, the definition of the current operator

$$\hat{J} = \frac{e\hbar}{m^*} \frac{\partial}{\partial x}.$$

Show that, for a state  $\psi(x) = \exp(ikz)$  representing an electron moving freely along the length of a quantum wire, the eigenvalue of  $\hat{J}$  has a magnitude  $ev_g$ .

[5 marks]

d) Show that when the quantum wire connects a reservoir of charge to a sink of charge with a potential difference |V| between them, the electrical conductance is quantised in units proportional to S where  $S^{-1} = 25.2 \text{ k}\Omega$ .

[5 marks]

e) Describe the conditions under which one might observe these quantised steps.

[2 marks]

4)

- a) Explain the relaxation oscillations in the building up of charge (and voltage) across an ultra small tunnel junction. [4 marks]
- b) Estimate the temperature at which a  $20 \times 20 \text{ nm}^2$  parallel-plate tunnelling capacitor with a thickness of 2 nm of insulating  $\text{Al}_2\text{O}_3$  layer is expected to show Coulomb blockade. What would be the threshold voltage? ( $\epsilon_r = 2 \text{ for Al}_2\text{O}_3$ ). [6 marks]
- c) A certain conductor has the shape of a strip with the dimensions  $L_x=1000$  nm in the direction of the electrical current,  $L_y=10$  nm and  $L_z=2$  nm in the transverse directions. The elastic scattering rate for the conduction electrons,  $\tau^{-1}=2\times 10^{14}~{\rm s}^{-1}$ ; the phase breaking rate,  $\tau_{\phi}^{-1}$ , changes with temperature according to the law  $\tau_{\phi}^{-1}=AT^3~{\rm s}^{-1}$ ;  $A=3\times 10^8~{\rm s}^{-1}~{\rm K}^{-3}$ ; and the Fermi velocity,  $v_F=2\times 10^6~{\rm m~s}^{-1}$ .
  - i) Calculate the temperature at which the conductor reaches the 1D regime with respect to the weak localisation effect. [6 marks]
  - ii) Sketch the dependence of the resistance of the conductor in the 1D weak localisation regime on magnetic field for two orientations: (1) parallel to the 0z axis, and (2) parallel to the 0y axis. [4 marks]

5)

- a) Describe the Dolan bridge technique for nanofabrication of sub-micron tunnel junctions. [4 marks]
- b) Explain the mechanism for the proximity effect which occurs during electron beam lithography. Describe how corrections may be applied to minimise the results of the proximity effect. How may the sample configuration be altered to minimise the effect? [6 marks]
- c) Describe the negative resist process for patterning a thin film using electronbeam lithography. Describe briefly the phenomenon taking place during the exposure of negative resist with an electron beam. [5 marks]
- d) Sketch the DC diode system for sputter deposition. How can the system be converted to generate plasma dry etch for use during the negative-resist lithography process? [5 marks]